



# SOT1360-2

plastic thermal enhanced extremely thin quad flat package;  
no leads; 20 terminals; body 3.5 x 5.5 x 0.85 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	HVSON
<b>Package type industry code</b>	HVSON20
<b>Package style descriptive code</b>	HXQFN (thermal enhanced extremely thin quad flatpack; no leads)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	11-5-2015

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	5.4	-	5.5	5.6	mm
E	package width	3.4	-	3.5	3.6	mm
A	seated height	0.8	-	0.85	1	mm
e	nominal pitch	-	-	0.5	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	20	-	

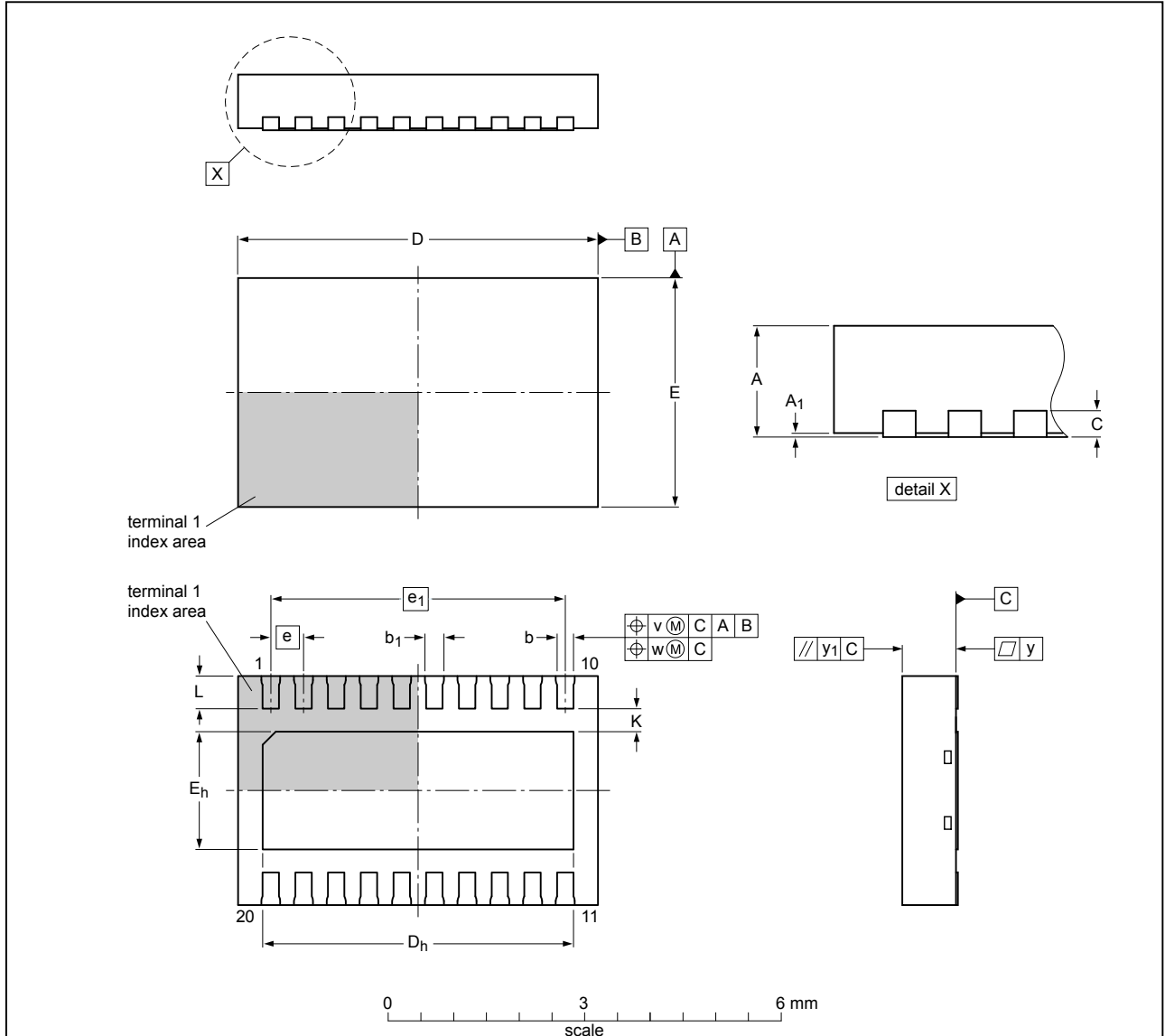


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## 2. Package outline

HVSON20: plastic thermal enhanced extremely thin quad flat package; no leads; 20 terminals; body 3.5 x 5.5 x 0.85 mm

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Dimensions

Unit	A <sup>(1)</sup>	A <sub>1</sub>	b	b <sub>1</sub>	C	D <sup>(1)</sup>	D <sub>h</sub>	E <sup>(1)</sup>	E <sub>h</sub>	e	e <sub>1</sub>	K	L	v	w	y	y <sub>1</sub>
max	1.00	0.05	0.30	0.32		5.6	5.05	3.6	1.85			0.40	0.55				
mm nom	0.85	0.03	0.25	0.27	0.20	5.5	5.00	3.5	1.80	0.5	4.5	0.35	0.50	0.1	0.05	0.05	0.1
min	0.80	0.00	0.20	0.22		5.4	4.95	3.4	1.75			0.30	0.45				

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included

sot1360-2\_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1360-2		MO-240			-15-09-17- 15-09-18

Fig. 1. Package outline HVSON20 (SOT1360-2)

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### 3. Legal information

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